

ITEMS		Parameter
		Double side & Multi-layer
Number of Layers		1-20 layers
Board Materials		FR-4 CEM-3 CEM-1 (TG150 TG170 CTI600)
PCB Size (Min- Max)		50x80mm to 1000mm×600mm (39.37"x23.6")
innerlayer line width/space(min)		4mil/4mil(100um/100um)
Finish Plating /Surface Finishes		HASL 、OSP、ENIG、gold finger,Au Panel,OSP,ENIG,
innerlayer pad (min)		5mil(0.13mm)
Core thickness (min)		8mli(0.2mm)
Finisher Copper Inner Layers		1/2oz(17um)a-
Finished Copper Outer Layers		1/2oz(17um)
Final PCB Thickness (tolerance %)		0.5-4.0mm
Final PCB Thickness (tolerance %)	Thickness<1.0mm	±12%
	1.0mm≤Thickness<2.0mm	±8%
		±10%
	Thickness≥2.0mm	±10%
inner layer process		Brown Oxide
Minimum Conductor Space		±3mil(±76um)
Minimum Drill Hole Size		0.2mm
min diameter of finished hole		0.2mm
Hole position accuracy		±2mil(±50um)
Drilled slot tolerance		±3mil(±75um)
NPTH tolerance		±3mil(±75um)
NPTH tolerance		±2mil(±50um)
maxA. R. Of PTH		8:1
PTH hole copper thickness		0.4-2mil(10-50um)
image to image tolerance		±3mil(0.075mm)
outer layer line width/space(min)		4mil/5mil
Solder Mask Thickness	line end	0.4-1.2mil(10-30um)
	line Corner	≥0.2mil(5um)
	on Substrate	≤+1.2mm≤+30um) ≤+1.2mil≤+30um)
min solder mask dam		4.0mil(100um)
impedance control and tolerance		50Ω ±10%/90Ω ±10%/100Ω ±10%
warp and twist		≤0.75%
Delivery time		1-2 layers 3-5days
		4-20 layers 7-10days
Package		